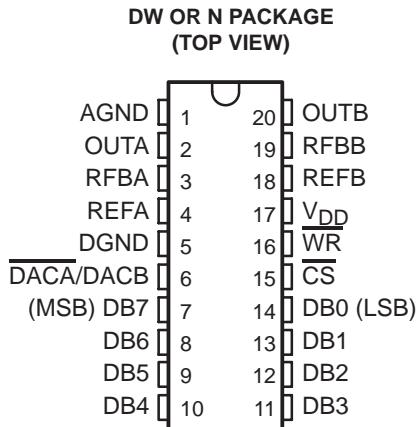


**TLC7628C**  
**DUAL 8-BIT MULTIPLYING**  
**DIGITAL-TO-ANALOG CONVERTER**  
 SLAS063B - APRIL 1989 - REVISED MARCH 2007

- Easy Microprocessor Interface
- On-Chip Data Latches
- Digital Inputs Are TTL-Compatible With 10.8-V to 15.75-V Power Supply
- Monotonic Over the Entire A/D Conversion Range
- Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 bits
Linearity Error	1/2 LSB
Power Dissipation	20 mW
Settling Time	100 ns
Propagation Delay Time	80 ns



### description

The TLC7628C is a dual, 8-bit, digital-to-analog converter (DAC) designed with separate on-chip data latches and featuring exceptionally close DAC-to-DAC matching. Data are transferred to either of the two DAC data latches through a common, 8-bit input port. Control input  $\overline{\text{DACA}}/\text{DACB}$  determines which DAC is loaded. The load cycle of this device is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

The TLC7628C operates from a 10.8-V to 15.75-V power supply and is TTL-compatible over this range. 2- or 4-quadrant multiplying makes this device a sound choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7628C is characterized for operation from 0°C to +70°C.



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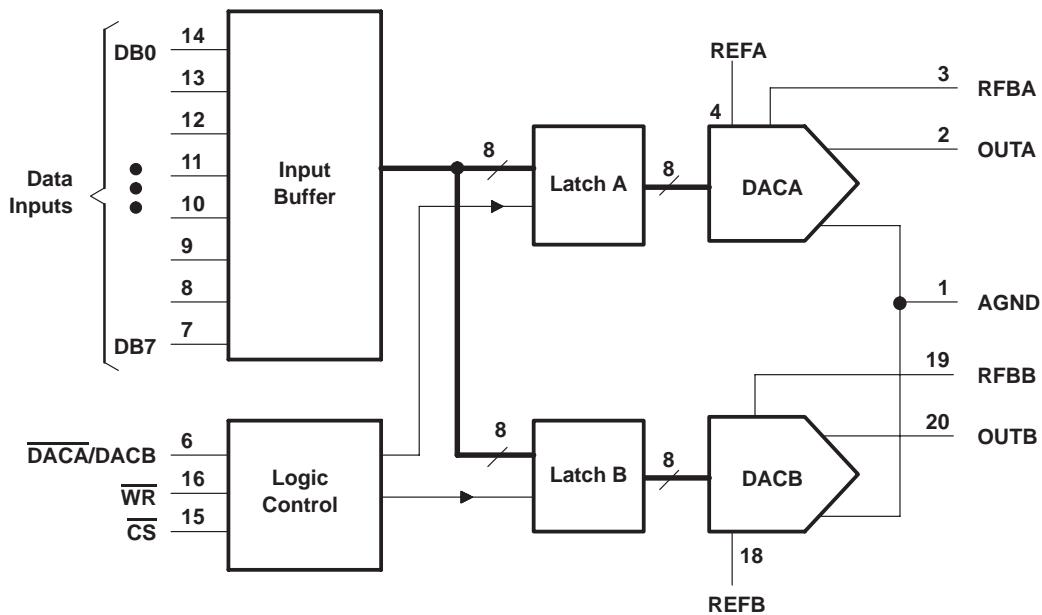
**PRODUCTION DATA** information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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# TLC7628C DUAL 8-BIT MULTIPLYING

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## functional block diagram



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{DD}$ (to AGND or DGND) .....	-0.3 V to 17 V
Voltage between AGND and DGND .....	$V_{DD}$
Input voltage range, $V_I$ (to DGND) .....	-0.3 V to $V_{DD} + 0.3$ V
Reference voltage range, $V_{refA}$ or $V_{refB}$ (to AGND) .....	$\pm 25$ V
Feedback voltage range, $V_{RFBA}$ or $V_{RFBB}$ (to AGND) .....	$\pm 25$ V
Output voltage range, $V_{OA}$ or $V_{OB}$ (to AGND) .....	$\pm 25$ V
Peak input current .....	10 $\mu$ A
Operating free-air temperature range, $T_A$ : TLC7628C .....	0°C to +70°C
Storage temperature range, $T_{stg}$ .....	-65°C to +150°C
Case temperature for 10 seconds, $T_C$ : FN package .....	+260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package .....	+260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**recommended operating conditions**

		MIN	NOM	MAX	UNIT
Supply voltage, $V_{DD}$		10.8		15.75	V
Reference voltage, $V_{refA}$ or $V_{refB}$			$\pm 10$		V
High-level input voltage, $V_{IH}$		2.4			V
Low-level input voltage, $V_{IL}$			0.8		V
CS setup time, $t_{su}(CS)$		50			ns
CS hold time, $t_h(CS)$ (see Figure 1)		0			ns
DAC select setup time, $t_{su}(DAC)$ (see Figure 1)		60			ns
DAC select hold time, $t_h(DAC)$ (see Figure 1)		10			ns
Data bus input setup time $t_{su}(D)$ (see Figure 1)		25			ns
Data bus input hold time $t_h(D)$ (see Figure 1)		10			ns
Pulse duration, $\overline{WR}$ low, $t_w(WR)$ (see Figure 1)		50			ns
Operating free-air temperature, $T_A$	TLC7628C	0	+70		°C

**electrical characteristics over recommended ranges of operating free-air temperature and  $V_{DD}$ ,  $V_{refA} = V_{refB} = 10$  V,  $V_{OA}$  and  $V_{OB}$  at 0 V (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT	
$I_{IH}$	High-level input current	$V_I = V_{DD}$	Full range	10		$\mu A$	
			25°C	1			
$I_{IL}$	Low-level input current	$V_I = 0$	Full range	-10		$\mu A$	
			25°C	-1			
Reference input impedance REFA or REFB to AGND				5	20	kΩ	
$I_{kg}$	Output leakage current	OUTA	DAC data latch loaded with 00000000, $V_{refA} = \pm 10$ V	Full range	$\pm 200$	$nA$	
				25°C	$\pm 50$		
	OUTB		DAC data latch loaded with 00000000, $V_{refB} = \pm 10$ V	Full range	$\pm 200$		
				25°C	$\pm 50$		
Input resistance match (REFA to REFB)					$\pm 1\%$		
DC supply sensitivity $\Delta$ gain/ $\Delta V_{DD}$		$\Delta V_{DD} = \pm 5\%$	Full range	0.02		%/%	
			25°C	0.01			
$I_{DD}$	Supply current	Quiescent	All digital inputs at $V_{IH}$ min or $V_{IL}$ max		2	$mA$	
		Standby	All digital inputs at 0 V or $V_{DD}$	Full range	0.5		
				25°C	0.1		
$C_i$	Input capacitance	DB0–DB7			10	$pF$	
		WR, CS, DACA/DACB			15		
$C_o$	Output capacitance (OUTA, OUTB)		DAC data latches loaded with 00000000		25	$pF$	
			DAC data latches loaded with 11111111		60		

# TLC7628C

## DUAL 8-BIT MULTIPLYING

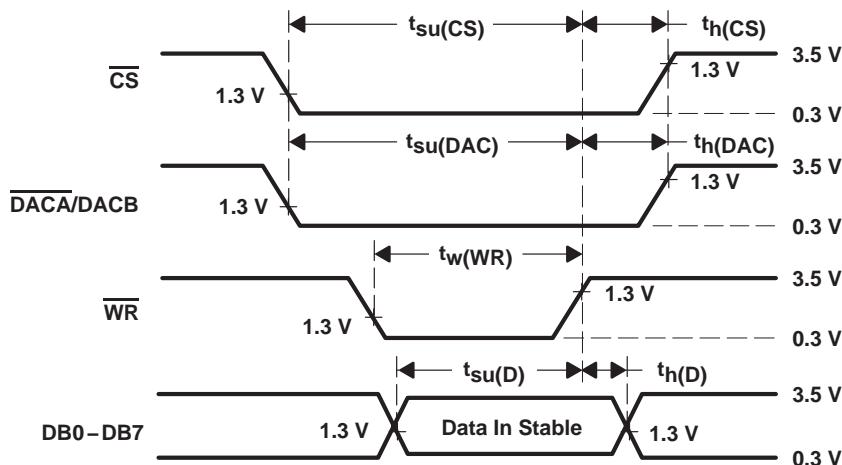
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**operating characteristics over recommended ranges of operating free-air temperature and  $V_{DD}$ ,  $V_{refA} = V_{refB} = 10$  V,  $V_{OA}$  and  $V_{OB}$  at 0 V (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Linearity error				$\pm 1/2$		LSB
Settling time (to 1/2 LSB)	See Note 1			100		ns
Gain error	See Note 2	Full range		$\pm 3$		LSB
		25°C		$\pm 2$		
AC feedthrough	REFA to OUTA	See Note 3	Full range		-65	dB
	REFB to OUTB		25°C		-75	
Temperature coefficient of gain				$\pm 0.0035$		%FSR/°C
Propagation delay (from digital input to 90% of final analog output current)	See Note 4			80		ns
Channel-to-channel isolation	REFA to OUTB	See Note 5	25°C		80	dB
	REFB to OUTA	See Note 6	25°C		80	
Digital-to-analog glitch impulse area	Measured for code transition from 00000000 to 11111111, $T_A = 25$ °C			330		nV•s
Digital crosstalk	Measured for code transition from 00000000 to 11111111, $T_A = 25$ °C			60		nV•s
Harmonic distortion	$V_i = 6$ V, $f = 1$ kHz, $T_A = 25$ °C			-85		dB

NOTES: 1. OUTA, OUTB load = 100  $\Omega$ ,  $C_{ext} = 13$  pF;  $\overline{WR}$  and  $\overline{CS}$  at 0 V; DB0–DB7 at 0 V to  $V_{DD}$  or  $V_{DD}$  to 0 V.

2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) =  $V_{ref} - 1$  LSB. Both DAC latches are loaded with 11111111.
3.  $V_{ref} = 20$  V peak-to-peak, 10-kHz sine wave
4.  $V_{refA} = V_{refB} = 10$  V; OUTA/OUTB load = 100  $\Omega$ ,  $C_{ext} = 13$  pF;  $\overline{WR}$  and  $\overline{CS}$  at 0 V; DB0–DB7 at 0 V to  $V_{DD}$  or  $V_{DD}$  to 0 V.
5.  $V_{refA} = 20$  V peak-to-peak, 10-kHz sine wave;  $V_{refB} = 0$
6.  $V_{refB} = 20$  V peak-to-peak, 10-kHz sine wave;  $V_{refA} = 0$

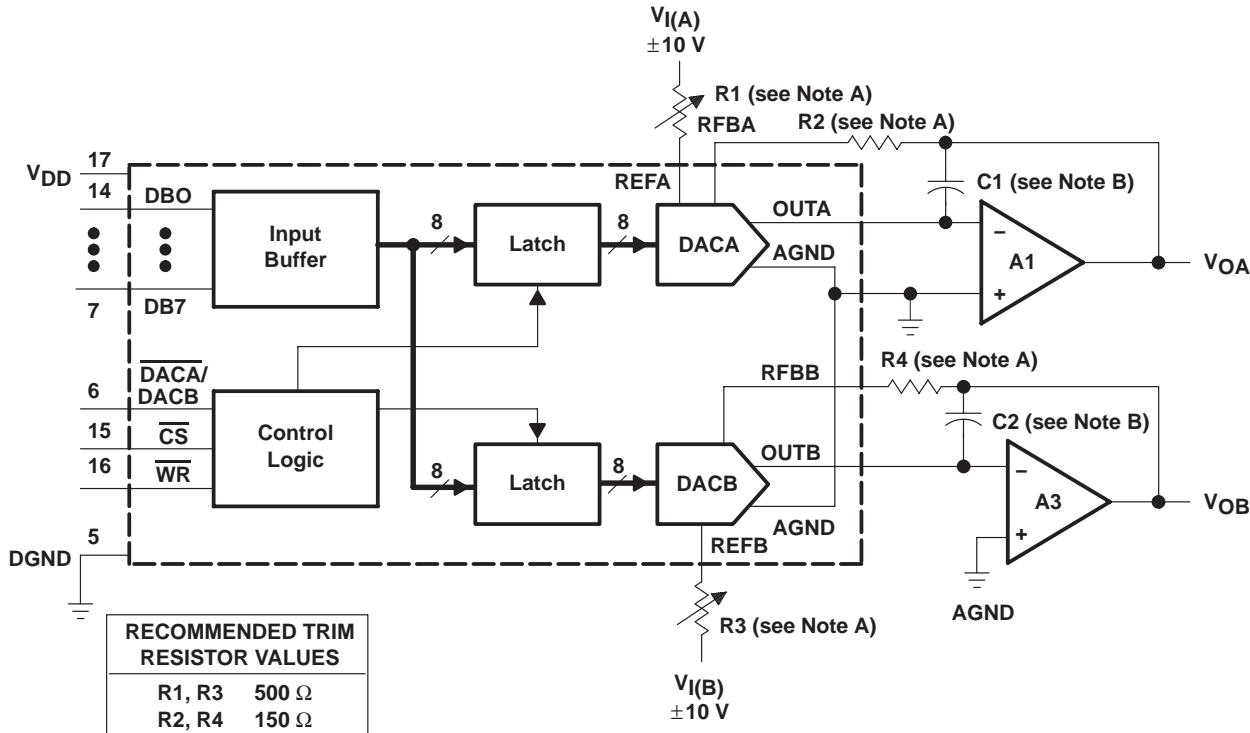


For all input signals,  $t_r = t_f = 5$  ns (10% to 90% points).

Figure 1. Setup and Hold Times

## APPLICATION INFORMATION

This device is capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figures 2 and 3. Input coding for unipolar and bipolar operation are summarized in Tables 2 and 3, respectively.



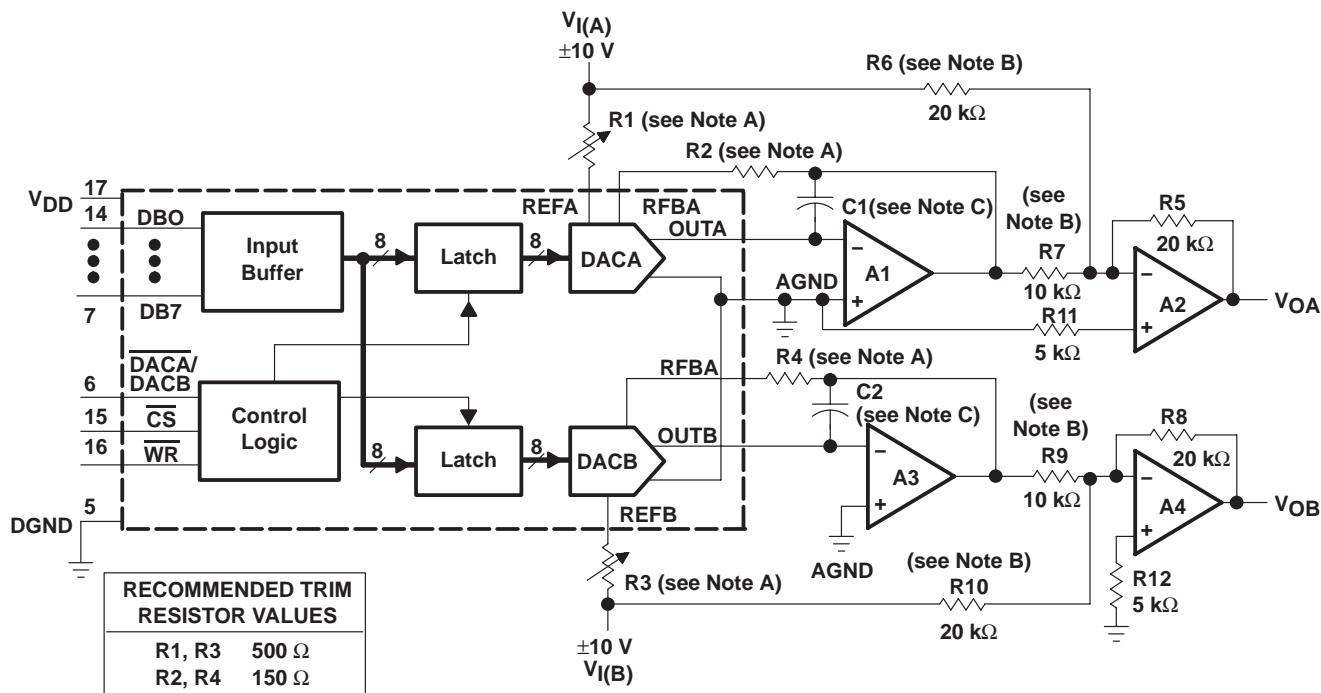
NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.  
 B. C1 and C2 phase compensation capacitors (10 pF to 15 pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

**Figure 2. Unipolar Operation (2-Quadrant Multiplication)**

# TLC7628C DUAL 8-BIT MULTIPLYING

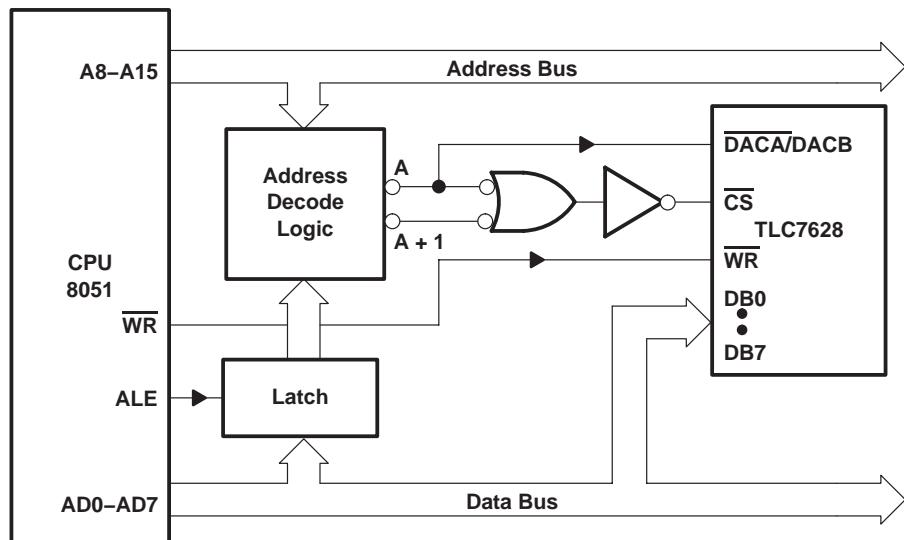
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## APPLICATION INFORMATION



NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Adjust R1 for  $V_{OA} = 0$  V with code 10000000 in DACA latch. Adjust R3 for  $V_{OB} = 0$  V with 10000000 in DACB latch.  
 B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.  
 C. C1 and C2 phase compensation capacitors (10 pF to 15 pF) may be required if A1 and A3 are high-speed amplifiers.

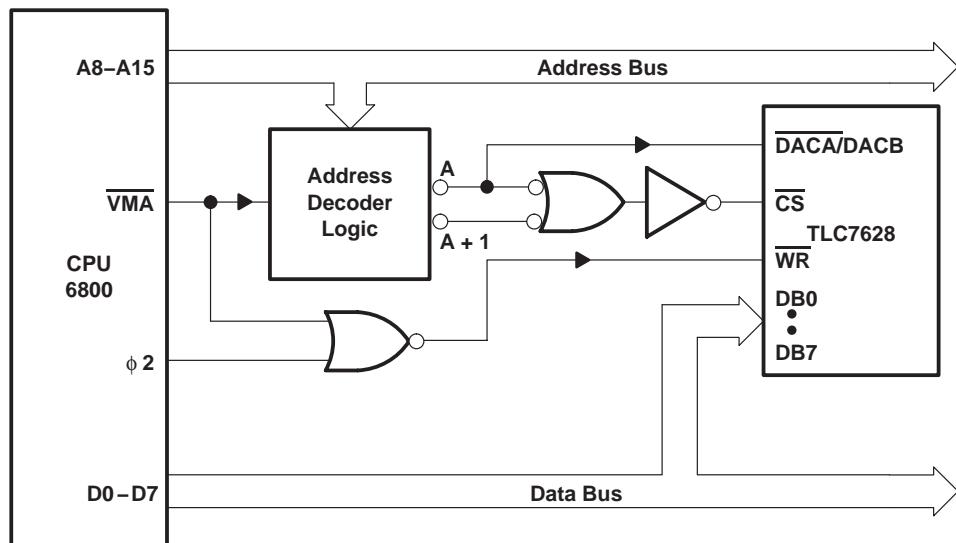
Figure 3. Bipolar Operation (4-Quadrant Operation)



NOTE D: A = decoded address for TLC7628 DACA  
 A + 1 = decoded address for TLC7628 DACB

Figure 4. TLC7628 — Intel 8051 Interface

## APPLICATION INFORMATION



NOTE D: A = decoded address for TLC7628 DACA  
A + 1 = decoded address for TLC7628 DACB

**Figure 5. TLC7628 – 6800 Interface**

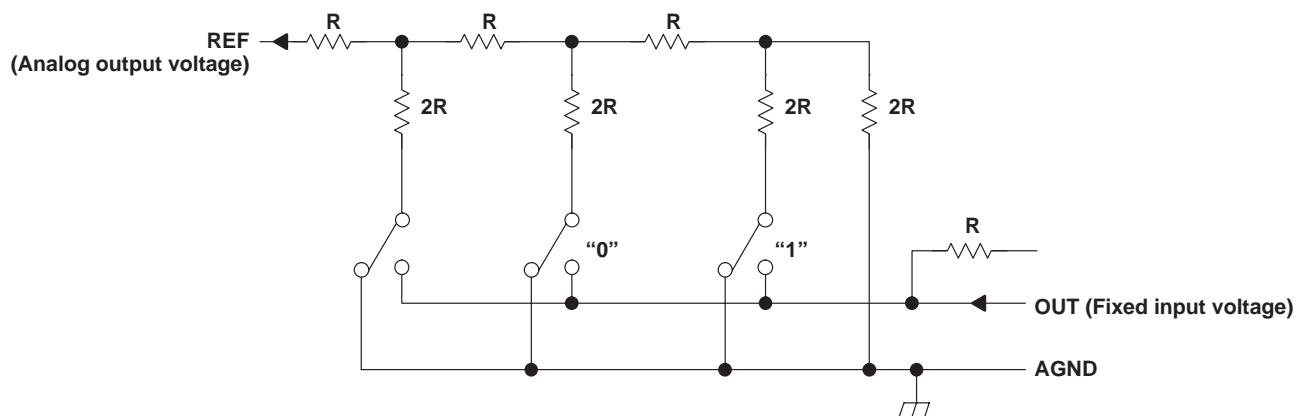
## voltage-mode operation

The current-multiplying DAC in the TLC7628C can be operated in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. An example of a current-multiplying DAC operating in voltage mode is shown in Figure 6. The relationship between the fixed input voltage and the analog output voltage is given by the following equation:

Analog output voltage = fixed input voltage (D/256)

where  $D$  = the digital input. In voltage-mode operation, these devices meet the following specification:

LINEARITY ERROR	TEST CONDITIONS	MIN	MAX	UNIT
Analog output voltage for REFA, REFB	$V_{DD} = 12 \text{ V}$ , OUTA or OUTB at 5 V, $T_A = 25^\circ\text{C}$		1	LSB



**Figure 6. Current-Multiplying DAC Operating in Voltage Mode**

# TLC7628C DUAL 8-BIT MULTIPLYING

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## PRINCIPLES OF OPERATION

This device contains two, identical, 8-bit, multiplying DACs: DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between the DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified D/A circuit for DACA or DACB with all digital inputs low is shown in Figure 7.

Figure 8 shows the DACA or DACB equivalent circuit. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the reference current flows to OUTA. A small leakage current ( $I_{lkg}$ ) flows across internal junctions, and as with most semiconductor devices, doubles every  $10^{\circ}\text{C}$ . The  $C_o$  is caused by the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of  $C_o$  is 25 pF to 60 pF maximum. The equivalent output resistance ( $r_o$ ) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

The TLC7628C interfaces to a microprocessor through the data bus,  $\overline{\text{CS}}$ ,  $\overline{\text{WR}}$ , and  $\overline{\text{DACA/DACB}}$  control signals. When  $\overline{\text{CS}}$  and  $\overline{\text{WR}}$  are both low, the analog output on this device, specified by the  $\overline{\text{DACA/DACB}}$  control line, responds to the activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the  $\overline{\text{CS}}$  signal or  $\overline{\text{WR}}$  signal goes high, the data on the DB0–DB7 inputs are latched until the  $\overline{\text{CS}}$  and  $\overline{\text{WR}}$  signals go low again. When  $\overline{\text{CS}}$  is high, the data inputs are disabled, regardless of the state of the  $\overline{\text{WR}}$  signal.

The digital inputs of the TLC7628C provides TTL compatibility when operated from a supply voltage of 10.8 V to 15.75 V.

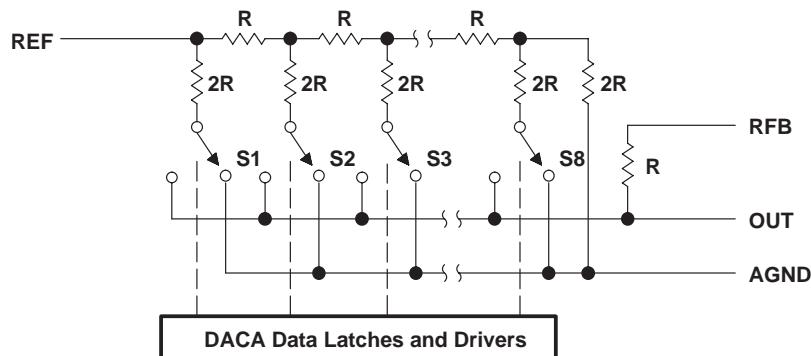


Figure 7. Simplified Functional Circuit for DACA or DACB

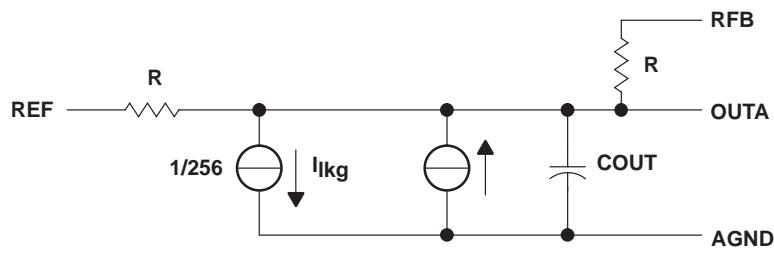


Figure 8. TLC7628 Equivalent Circuit for DACA or DACB

## PRINCIPLES OF OPERATION

**Table 1. Mode Selection Table**

DACA/DACB	CS	WR	DACA	DACB
L	L	L	Write	Hold
H	L	L	Hold	Write
X	H	X	Hold	Hold
X	X	H	Hold	Hold

L = low level, H = high level, X = don't care

**Table 2. Unipolar Binary Code**

DAC LATCH CONTENTS (see Note 7)		ANALOG OUTPUT
MSB	LSB	
1 1 1 1 1 1 1 1		$-V_I$ (255/256)
1 0 0 0 0 0 0 1		$-V_I$ (129/256)
1 0 0 0 0 0 0 0		$-V_I$ (128/256) = $-V_I/2$
0 1 1 1 1 1 1 1		$-V_I$ (127/256)
0 0 0 0 0 0 0 1		$-V_I$ (1/256)
0 0 0 0 0 0 0 0		$-V_I$ (0/256) = 0

NOTES: 7. 1 LSB =  $(2 - 8)V_I$   
8. 1 LSB =  $(2 - 7)V_I$

**Table 3. Bipolar (Offset Binary) Code**

DAC LATCH CONTENTS (see Note 8)		ANALOG OUTPUT
MSB	LSB	
1 1 1 1 1 1 1 1		$V_I$ (127/128)
1 0 0 0 0 0 0 1		$V_I$ (1/128)
1 0 0 0 0 0 0 0		0 V
0 1 1 1 1 1 1 1		$-V_I$ (1/128)
0 0 0 0 0 0 0 1		$-V_I$ (127/128)
0 0 0 0 0 0 0 0		$-V_I$ (128/128)

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLC7628CDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C
TLC7628CDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C
<a href="#">TLC7628CDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C
TLC7628CDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7628C
<a href="#">TLC7628CN</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLC7628CN
TLC7628CN.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLC7628CN

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

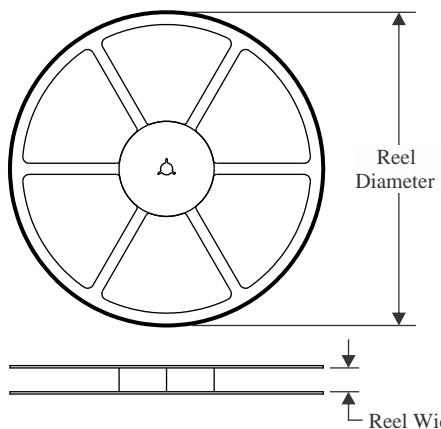
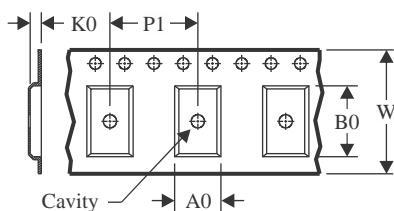
<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

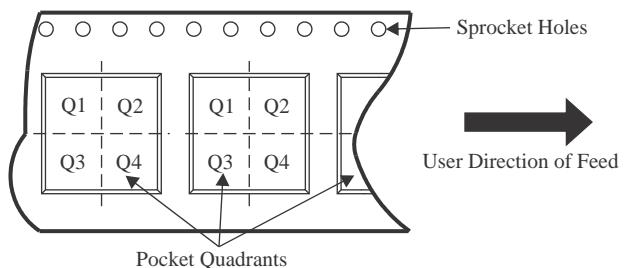
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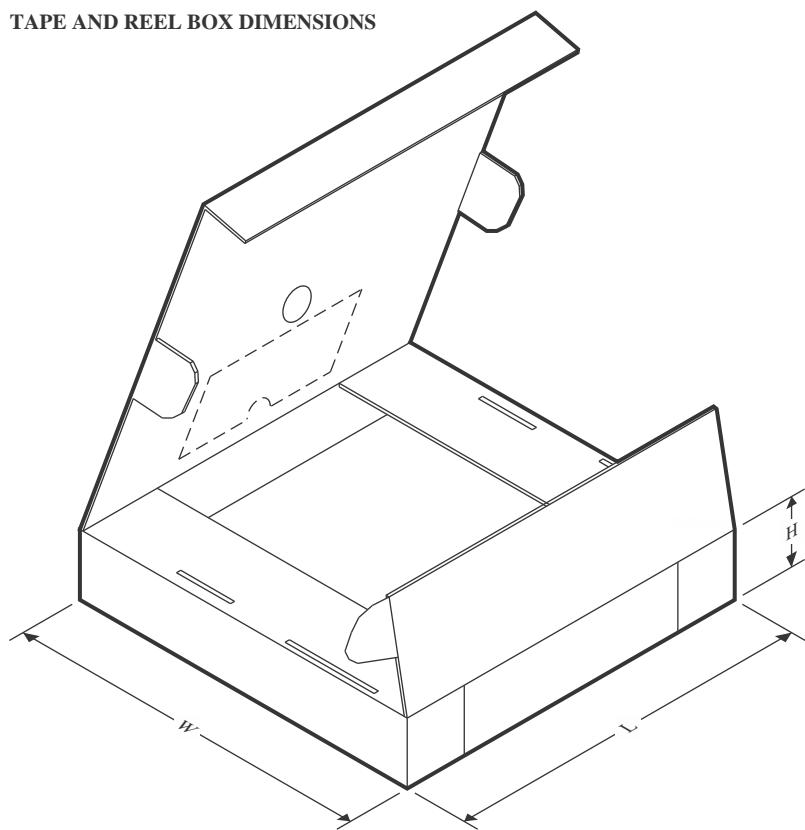
**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


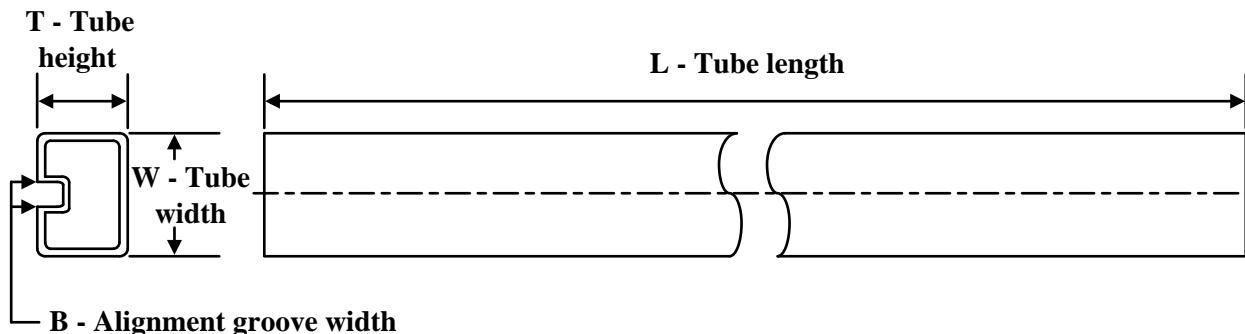
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC7628CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC7628CDWR	SOIC	DW	20	2000	350.0	350.0	43.0

**TUBE**


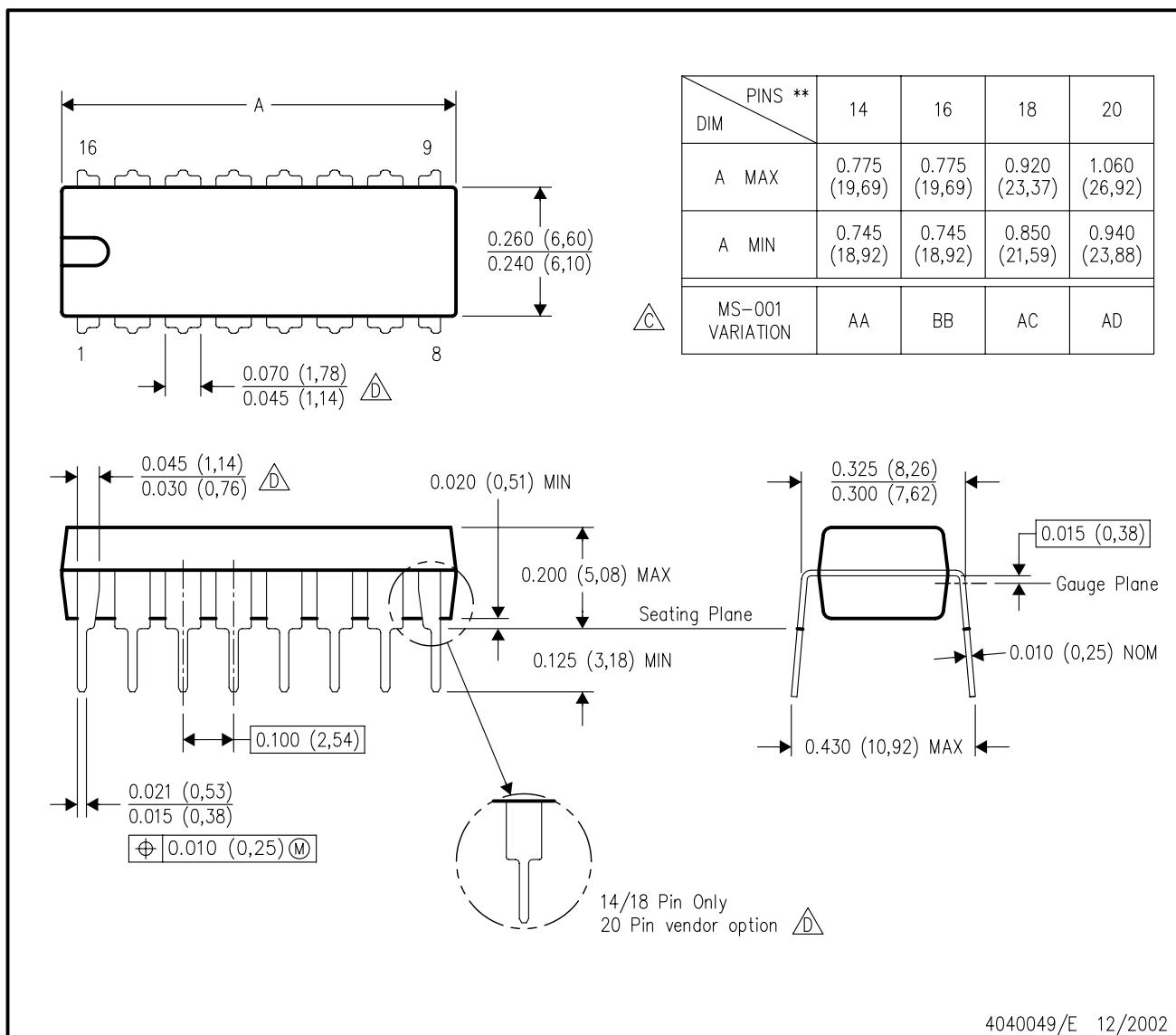
\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T ( $\mu$ m)	B (mm)
TLC7628CDW	DW	SOIC	20	25	506.98	12.7	4826	6.6
TLC7628CDW.A	DW	SOIC	20	25	506.98	12.7	4826	6.6
TLC7628CN	N	PDIP	20	20	506	13.97	11230	4.32
TLC7628CN.A	N	PDIP	20	20	506	13.97	11230	4.32

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

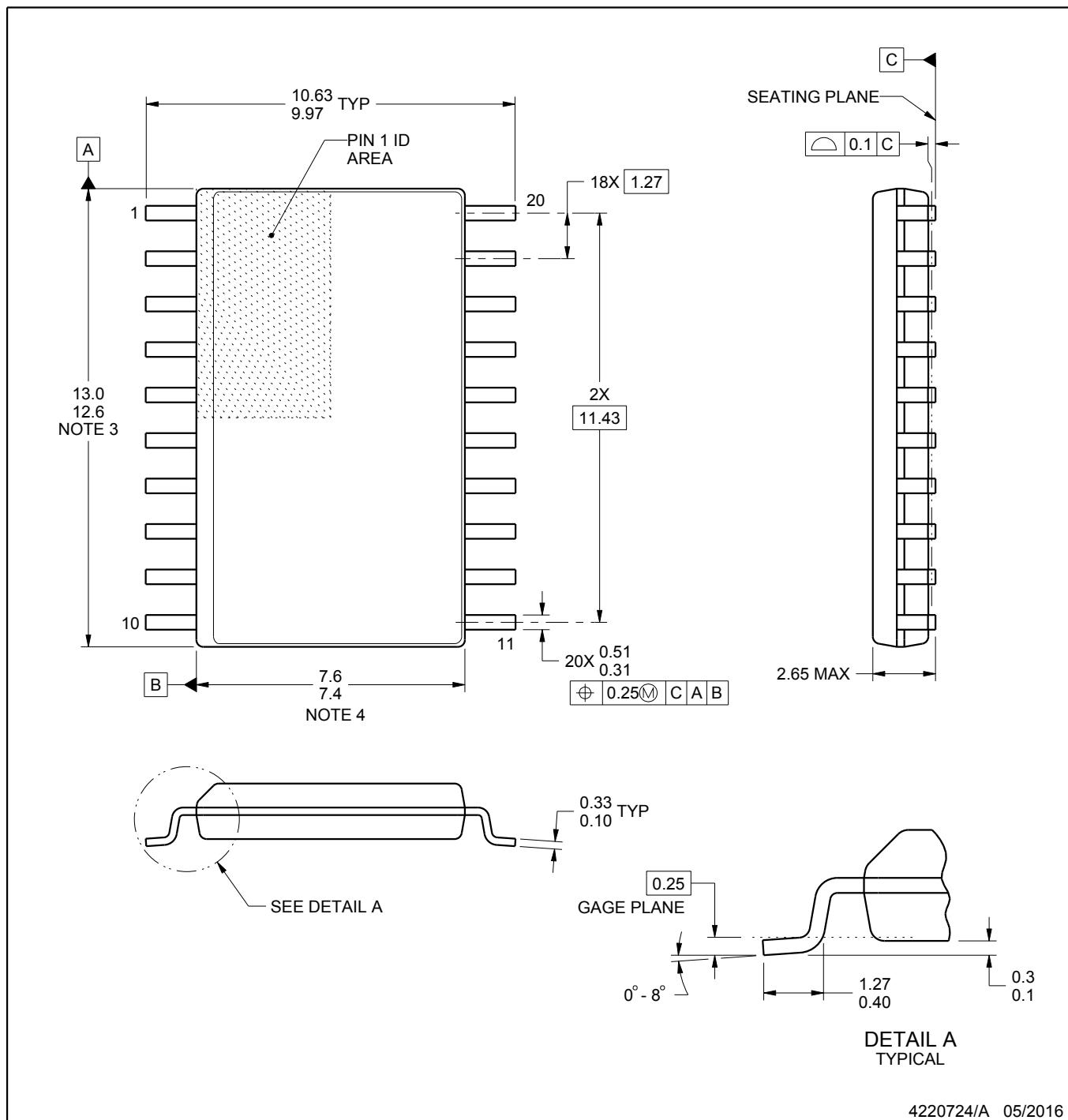


## PACKAGE OUTLINE

**DW0020A**

## **SOIC - 2.65 mm max height**

SOIG



## NOTES:

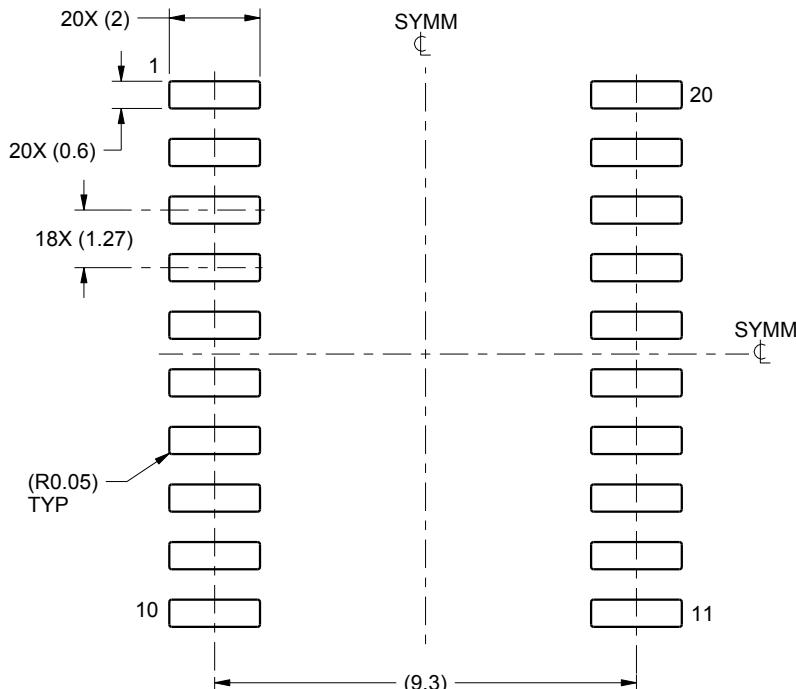
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

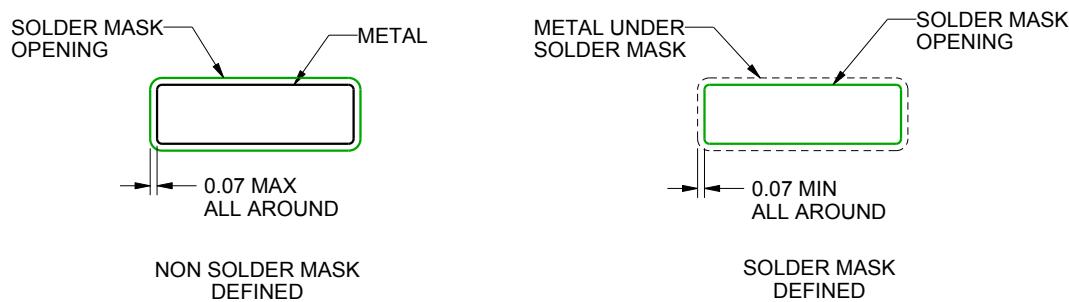
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

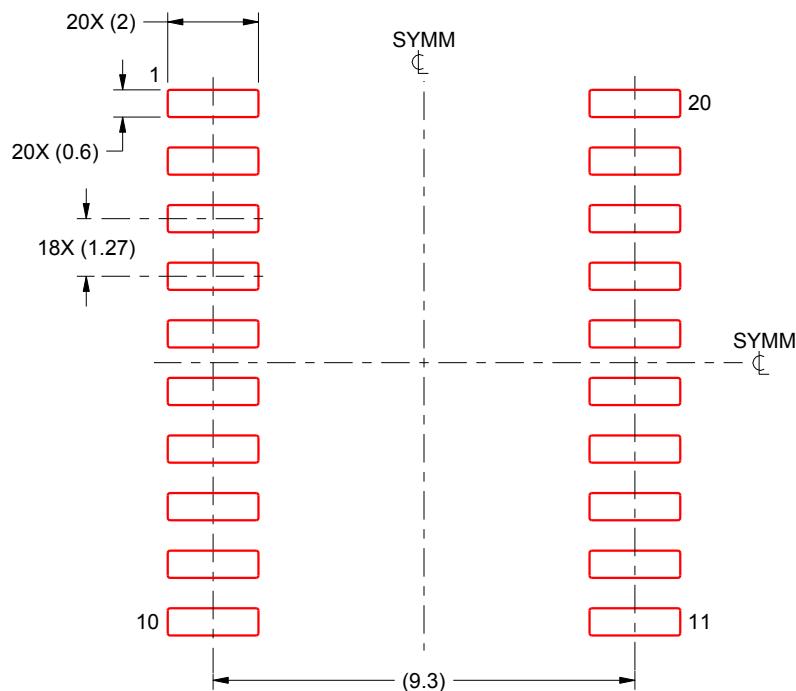
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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